

KYZEN® E5631J

Ready to Use Understencil Wipe

KYZEN E5631J is a ready-to-use solution for removing raw solder paste from stencils both in online and offline stencil cleaning processes. E5631J is a cost-effective solution that quickly and efficiently cleans all types of raw solder pastes to make every print count. KYZEN E5631J is proven compatible with common stencils, cleaning equipment, and printer manufacturers. The E5631J is formulated with the worker and environment in mind.



- **Improves Solder Paste Release from Even the Smallest of Apertures**
- **Does Not Interact or Remove Nano Coatings**
- **Low Cost of Ownership**
- **Compatible with Wetted Components in Automatic Stencil Printers**

PRODUCT PROPERTIES

pH	N/A (Solvent-Based)
FLASH POINT	None to Boiling
BOILING POINT	212°F/100°C
WATER SOLUBLE	Complete
VOC, @ 100%	131 g/L

TYPICAL PROCESSES

APPLICATION	Online & Offline Stencil Center
CONCENTRATION	Ready to Use
TEMPERATURE	Ambient - 120°F / 49°C
RINSE	DI Water / Solvent
DRY	Warm Air Recommended

The above process parameters are recommendations based on extensive testing done in KYZEN's application lab. Your KYZEN sales representative can assist you in optimizing your process parameters.

STORAGE AND HANDLING

- Packaged in Polyethylene Containers
- Store at 5-50°C/41-122°F in Original Container
- Standard Chemical Handling Practices
- Shelf Life of 5 Years, in Sealed Containers of 5 gallons / 25 liters or more

AVAILABILITY

- 1 Gallon
- 5 Gallons
- 5 Liters*
- 25 Liters*

* Liters Available in South Asia and Europe

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Ready to Use Understencil Cleaner



ENVIRONMENTAL, HEALTH AND SAFETY REGULATIONS

KYZEN E5631J is RoHs compliant and Halogen-free in accordance with RoHS Directive (EU) 2015/863 and EN 14582:2016. E5631J has a negligible global warming potential, is not regulated as an Ozone Depleting Chemical in the United States, and is not listed as a Hazardous Air Pollutant. Refer to the Safety Data Sheet for more information.

REACH ✓ KYZEN is an ISO 9001:2015 Certified Company

COMPATIBILITY

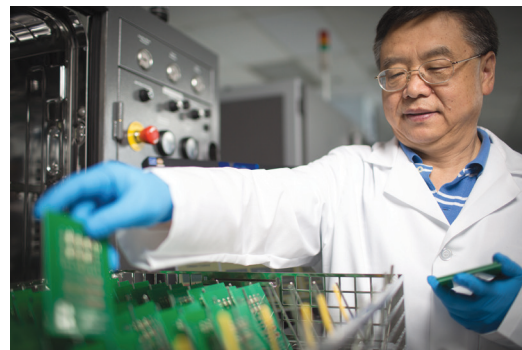
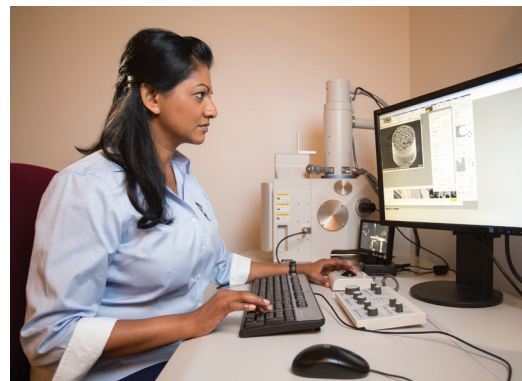
KYZEN E5631J is compatible with all materials commonly used in electronic assembly manufacturing and cleaning processes. For specific compatibility information, please contact your KYZEN representative.

FREE CLEANING TRIALS AND PROCESS OPTIMIZATIONS

KYZEN will conduct complimentary trials at your factory or “risk-free” testing in one of our global applications laboratories in North America, Asia or Europe to ensure you achieve your goal. Increase your yields and product reliability by identifying and tuning the critical parameters of your cleaning process. With our commitment to science and understanding process, KYZEN has the flexibility to simulate and refine any cleaning process.

Each laboratory is fully equipped with an extensive array of cleaning and analytical equipment including:

- Batch Washers
- In-Line Washers
- Ultrasonic Systems
- SUI Systems
- Vapor Degreasers
- GC (TCD and FID)
- Scanning Electron Microscope (SEM)
- Ion Chromatography
- FTIR Spectrophotometer
- Humidity Chamber
- High Powered Microscopes



**Aqueous, Semi-Aqueous and Vapor Phase Chemistries • Process Evaluation and Optimization
Contract Cleaning • Cleanliness Testing • Soil Analysis**

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